

Title (en)  
Solid-state imaging device

Title (de)  
Festkörperbildsensor

Title (fr)  
Dispositif d'imagerie à l'état solide

Publication  
**EP 1526578 A3 20060412 (EN)**

Application  
**EP 04025122 A 20041022**

Priority  
JP 2003363609 A 20031023

Abstract (en)  
[origin: EP1526578A2] A solid-state imaging-device includes a base, frame-shaped ribs provided on the base and forming an internal space, a plurality of wiring members for electrically leading the internal space of a housing formed by the base and the ribs to an external portion, an imaging element fixed to the base inside the internal space, a transparent plate fixed to an upper surface of the ribs, and connecting members electrically connecting electrodes of the imaging element to the wiring members, wherein a plurality of protrusions are provided in a region of the base that faces the imaging element, and the imaging element is fixed by adhesive to the base while being supported by the protrusions. The protrusions enable the imaging element to avoid distortion caused by following the surface of the base, thereby suppressing the effect on electrical properties of the imaging element.

IPC 8 full level  
**H01L 27/14** (2006.01); **H01L 31/0203** (2006.01); **H01L 23/02** (2006.01); **H01L 23/04** (2006.01); **H01L 23/08** (2006.01); **H01L 23/50** (2006.01); **H01L 27/146** (2006.01); **H04N 25/00** (2023.01)

CPC (source: EP KR US)  
**H01L 23/50** (2013.01 - KR); **H01L 24/32** (2013.01 - EP US); **H01L 24/97** (2013.01 - EP US); **H01L 27/14618** (2013.01 - EP US); **H01L 27/14683** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/48247** (2013.01 - EP US); **H01L 2224/73265** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US)

C-Set (source: EP US)  
1. **H01L 2224/48091 + H01L 2924/00014**  
2. **H01L 2924/181 + H01L 2924/00**

Citation (search report)  
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• [A] DE 20301346 U1 20030327 - KINGPAK TECH INC [TW]  
• [X] PATENT ABSTRACTS OF JAPAN vol. 2003, no. 07 3 July 2003 (2003-07-03)

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EP1758373A3

Designated contracting state (EPC)  
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)  
**EP 1526578 A2 20050427; EP 1526578 A3 20060412**; CN 100433301 C 20081112; CN 1610101 A 20050427; JP 2005129721 A 20050519; JP 3838573 B2 20061025; KR 100644180 B1 20061110; KR 20050039588 A 20050429; TW 200515575 A 20050501; US 2005088565 A1 20050428; US 2009290054 A1 20091126; US 7586529 B2 20090908; US 7719585 B2 20100518

DOCDB simple family (application)  
**EP 04025122 A 20041022**; CN 200410085932 A 20041025; JP 2003363609 A 20031023; KR 20040083974 A 20041020; TW 93131954 A 20041021; US 51056209 A 20090728; US 96982204 A 20041021